

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV70130DBVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV70130DBVR	NIPDAU	Level-1-260C-UNLIM	Ext-Mfg	DBV 5	2.9x1.6x1.45	18.3

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Precious Metals	Gold	7440-57-5	0.028536	100	1000000	0.1562	1562
Sub-Total			0.028536	100	1000000	0.1562	1562
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.09184	80	800000	0.502714	5027
Thermoplastics	Epoxy	85954-11-6	0.02296	20	200000	0.125679	1257
Sub-Total			0.1148	100	1000000	0.628393	6284
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.290748	97.38	973800	34.434323	344343
Copper and Its Alloys	Iron	7439-89-6	0.153748	2.38	23800	0.841586	8416
Copper and Its Alloys	Phosphorus	7723-14-0	0.005426	0.083994	840	0.029701	297
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.001938	0.03	300	0.010608	106
Zinc and Its Alloys	Zinc	7440-66-6	0.00814	0.126006	1260	0.044557	446
Sub-Total			6.46	100	1000000	35.360776	353608
Lead Frame Plating							
Nickel and Its Alloys	Nickel	7440-02-0	0.110339	95.119828	951198	0.603974	6040
Precious Metals	Gold	7440-57-5	0.000905	0.780172	7802	0.004954	50
Precious Metals	Palladium	7440-05-3	0.004756	4.1	41000	0.026033	260
Sub-Total			0.116	100	1000000	0.634961	6350
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	9.718331	85.999999	860000	53.196242	531962
Other Plastics and Rubber	Carbon Black	1333-86-4	0.056502	0.500001	5000	0.309281	3093
Thermoplastics	Epoxy	85954-11-6	1.525552	13.5	135000	8.350573	83506
Sub-Total			11.300385	100	1000000	61.856096	618561
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.249109	100	1000000	1.363574	13636
Sub-Total			0.249109	100	1000000	1.363574	13636
Total			18.26883			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSIs or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality
 For further environmental statements, please go to www.ti.com/ecoinfo
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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb203) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.